Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS)

TK80E08K3

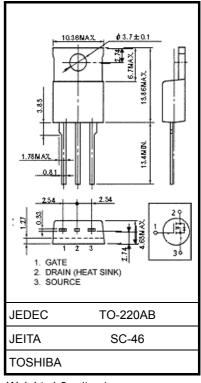
■ E-Bike/UPS/Inverter

• Low drain-source ON resistance : RDS (ON) = $7.5 \text{ m}\Omega$ (typ.) • High forward transfer admittance : $|Y_{fs}| = 135 \text{ S (typ.)}$ • Low leakage current : $I_{DSS} = 10 \text{ }\mu\text{A (max)} \text{ (V}_{DS} = 75 \text{ V)}$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics S		ymbol	Rating	Unit
Drain-source voltage		V _{DSS} 75		٧
Drain-gate voltage (R _{GS} = 20 kΩ) V		DGR 75		٧
Gate-source voltage		V _{GSS} ±20		٧
Drain current	DC (Note 1)	I _D 80		Α
	DC (Note 1,4)	I _D 70		Α
	Pulse (Note 1)	I _{DP} 240		Α
Drain power dissipation (Tc = 25°C)		P _D 200		W
Single pulse avalanche energy (Note 2)		E _{AS} 107		mJ
Avalanche current		I _{AR} 40		Α
Repetitive avalanche energy (Note 3)		E _{AR} 20		mJ
Peak diode recovery dv/dt (Note 5)		dv/dt	12	V/ns
Channel temperature (Note 4)		T _{ch} 175		°C
Storage temperature range (Note 4)		T _{stg}	-55~175	°C



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Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the signif (patt change in temperature, etc.) may cause this product to decrease in the relia bility significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Characteristics S	ymbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.75	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C / W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 100 $\mu H,~R_{G}$ = 25 $\Omega,~I_{AR}$ = 40A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

Note 4: Tc=100

Note 5: IDR 80A, di/dt 160A/µs, Tch Tch max.

This transistor is an electrostatic-sensitive device.

Please handle with caution.

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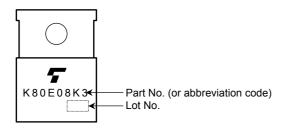
Electrical Characteristics (Ta = 25°C)

Charac	cteristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V	_	_	±1	μΑ
Drain cut-off cur	rrent	I _{DSS}	V _{DS} = 75 V, V _{DS} = 0 V	_	_	10	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	75		_	V
		V _{(BR) DSX}	I _D = 10 mA, V _{GS} = -20 V	45	1	1	V
Gate threshold v	oltage ·	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0		4.0	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 40 A	1	7.5	9.0	mΩ
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 40 A	67	135		S
Input capacitano	e	C _{iss} —			3600		
Reverse transfer capacitance		C _{rss} —	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		350		pF
Output capacitance		Coss			0		
Switching time	Rise time	t _r —	$\begin{array}{c} 10 \text{ V} \\ \text{VGS} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} \text{I}_D = 40 \text{ A} \\ \end{array}$ $\begin{array}{c} \text{V}_{OUT} \\ \text{O} \\ \end{array}$ $\begin{array}{c} \text{V}_{DD} \simeq 35 \text{ V} \\ \end{array}$ Duty \leq 1%, $t_W = 10 \mu\text{s}$		95	_	- ns
	Turn-on time	t _{on} —			135	ı	
	Fall time	t _f —			85		
	Turn-off time	t _{off}		— 22	0	_	
Total gate charge (Gate-source plus gate-drain)		Q _g —			75	_	
Gate-source charge		Q _{gs} —	$V_{DD} \approx 75 \text{ V, } V_{GS} = 10 \text{ V, } I_{D} = 80 \text{ A}$		44	_	nC
Gate-drain ("miller") charge		Q_{gd}				_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	80	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	240	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 80 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 80 A, V _{GS} = 0 V	1	45	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	— 72		_	μC

Marking



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